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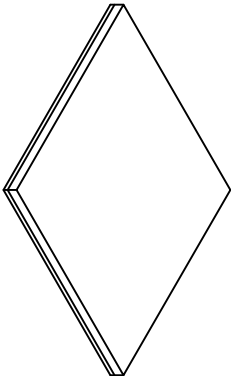
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REVISION HISTORY				
REV	DOI NUMBER	DESCRIPTION	ORIGINATOR	INCORPORATOR
00	C06693	INITIAL RELEASE	HLE	BWIEBB
01	C9800	ADDED 224 BALL MATRIX	ADEBO	DARNO
02	C9956	ADDED 208 BALL MATRIX	NALYA	NALYA
03	C10935	ADDED 228 BALL MATRIX	CHKO	CHKO
04	C16269	ADDED 241 BALL MATRIX	JOSEI	JOSEI
05	C20443	ADDED 220 BALL MATRIX	DSRYU	DSRYU



7. REFERENCE SPECIFICATIONS:
A. AAWW SPEC #001-0531-2234: PACKING OPERATION PROCEDURE.
B. AAWW SPEC #001-0519-2062: MARKING.

6. PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.

5. DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM C.

4. THE MAXIMUM ALLOWABLE NUMBER OF SOLDER BALLS IS 256.

3. THE MAXIMUM SOLDER BALL MATRIX SIZE IS 16 X 16.

2. THE BASIC SOLDER BALL GRID PITCH IS 1.00mm.

1. ALL DIMENSIONS AND TOLERANCES CONFORM TO ASME Y14.5M-1994.

NOTES: UNLESS OTHERWISE SPECIFIED

UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS		THIRD ANGLE PROJECTION		APPROVALS		DATE		TITLE		DATE		SIZE		SHEET	
DECIMAL	XX.XX	ANGULAR	±1°	DESIGNED	HOU LE	08/10/99	17.00mm X 17.00mm	PACKAGE OUTLINE - MAF, 16 X 16 MATRIX, 0.46mm BALL, 1.00mm PITCH, LAMINATE SUBSTRATE, AAWW	0.46mm	17.00mm	1.00mm	75910	05	1	OF 5
INTERPRET DIM AND TOL PER ASME Y14.5M - 1994				CHECKED	J. MICKSCH	08/10/99									
				PRODUCT MANAGER	T. PANICZAK	08/10/99									
				RELEASED	G. SCHULTZ	08/20/99									

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